

N-Channel Enhancement Mode MOSFET

Description

The CP100N04G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- $V_{DS} = 40V$, $I_D = 100A$
 $R_{DS(ON)}(Typ.) = 3.8m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)}(Typ.) = 5.1m\Omega$ @ $V_{GS} = 4.5V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Application

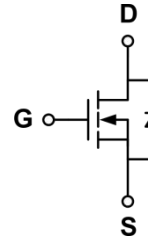
- PWM applications
- Load switch

Package

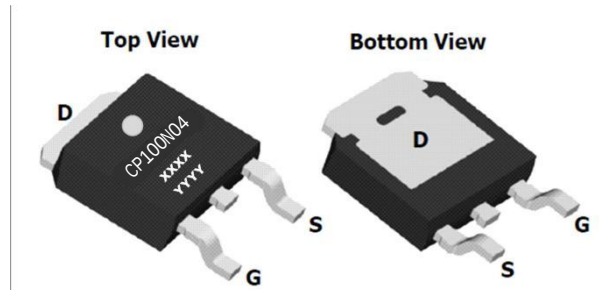
- TO-252-2L



Schematic diagram



Marking and pin assignment



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP100N04G-G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source voltage		V_{DS}	40	V
Gate-source voltage		V_{GS}	± 20	V
Continuous Drain Current	TC=25°C	I_D	100	A
	TC=70°C		70	
Pulsed Drain Current		I_{DM}	400	A
Avalanche energy ($V_{DD}=20V, V_G=10V, L=0.5mH, R_g=25\Omega$)		E_{AS}	299	mJ
power dissipation	TC=25°C	P_D	220	W
	TC=70°C		100	
Operating junction temperature range		T_j	-55~150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition		Min	Typ	Max	Unit
Static Characteristics							
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA		40	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	T _J =25°C	-	-	1	μA
			T _J =85°C			30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V		-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA		1.1	1.6	2.1	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =3A			3.8	4.6	mΩ
		V _{GS} =4.5V, I _D =2A		-	5.1	6.2	
Diode Characteristics							
Diode Continuous Forward Current	I _S			-	-	100	A
Reverse Recovery Time	t _{rr}	IF=20A, V _{GS} =0V		-	44	-	ns
Reverse Recovery Charge	I _S	dI/dt=100A/us		-	30	-	nC
Dynamic Characteristics ²							
Intrinsic gate resistance	R _G	V _{GS} =0V, V _{DS} =0V,f=1MHz		-	1.6	-	Ω
Input capacitance	C _{ISS}	V _{DS} =20V ,V _{GS} =0V f=1.0MHz		-	3987	-	pF
Output capacitance	C _{OSS}			-	285	-	
Reverse transfer capacitance	C _{RSS}			-	226	-	
Turn-on delay time	t _{D(ON)}	V _{DS} =20V,V _{GS} =10V R _L =2.6Ω,R _{GEN} =3Ω		-	11	-	ns
Turn-on Rise time	tr			-	15	-	
Turn-off delay time	t _{D(OFF)}			-	42	-	
Turn-off Fall time	tf			-	16	-	
Total gate charge	Qg	V _{DS} =20V I _D =3A V _{GS} =10V		-	68	-	nC
Gate-source charge	Qgs			-	9	-	
Gate-drain charge	Qgd			-	11	-	
Drain-Source Diode Characteristics							
Diode forward voltage	V _{SD}	V _{GS} =0V,I _S =3A		-	0.72	1.4	V

Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

Typical Performance Characteristics

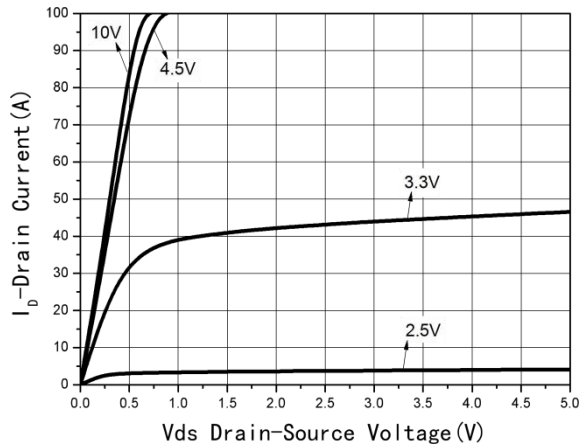
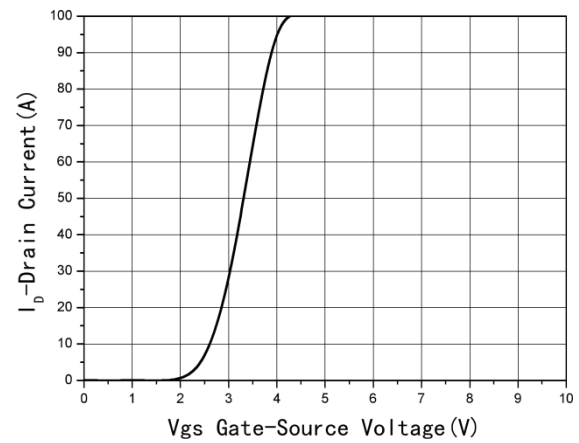
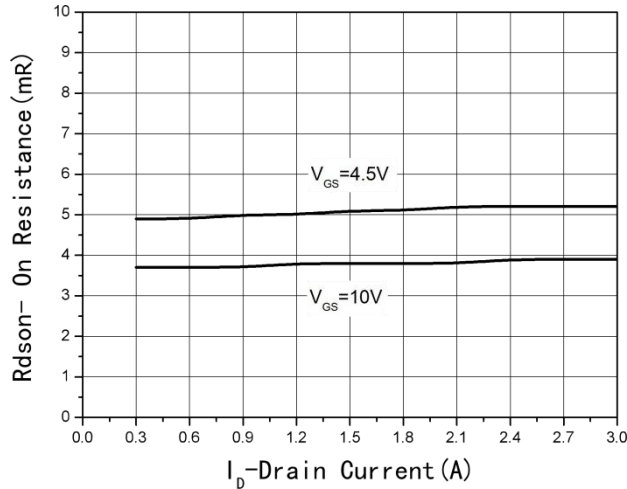
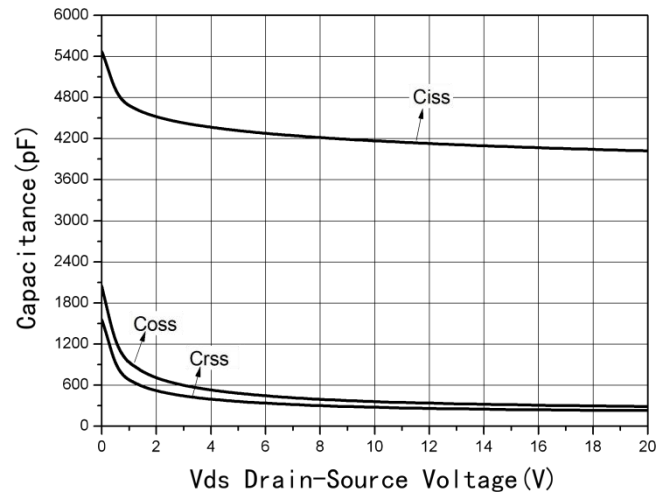
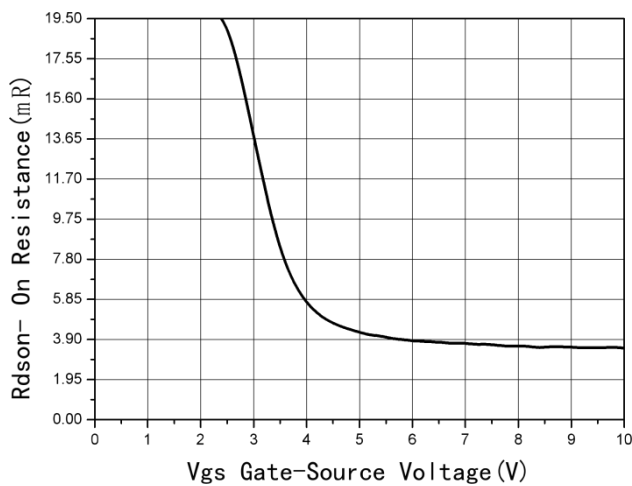
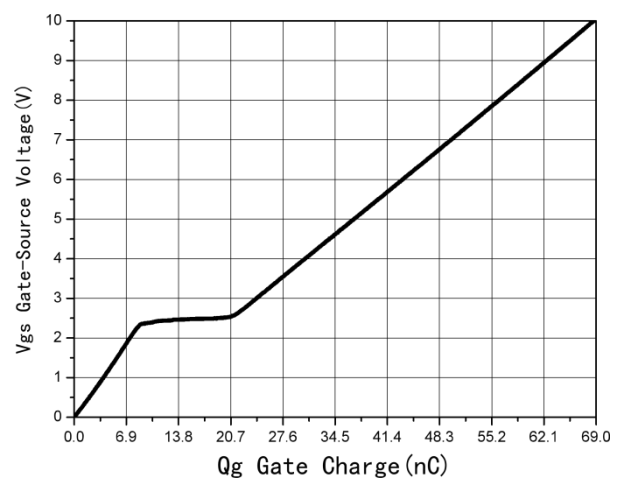
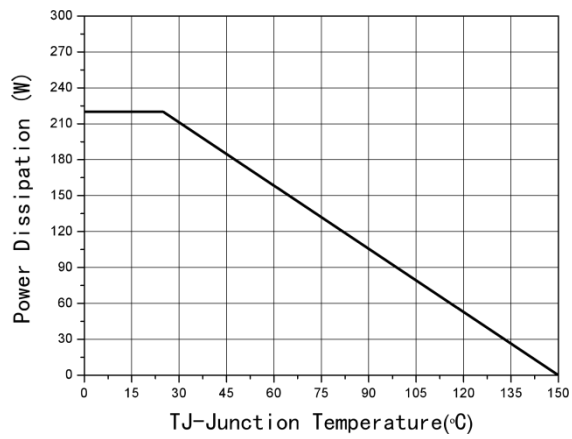
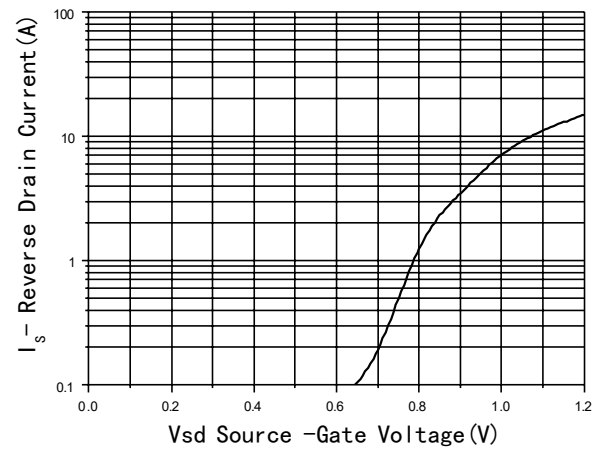
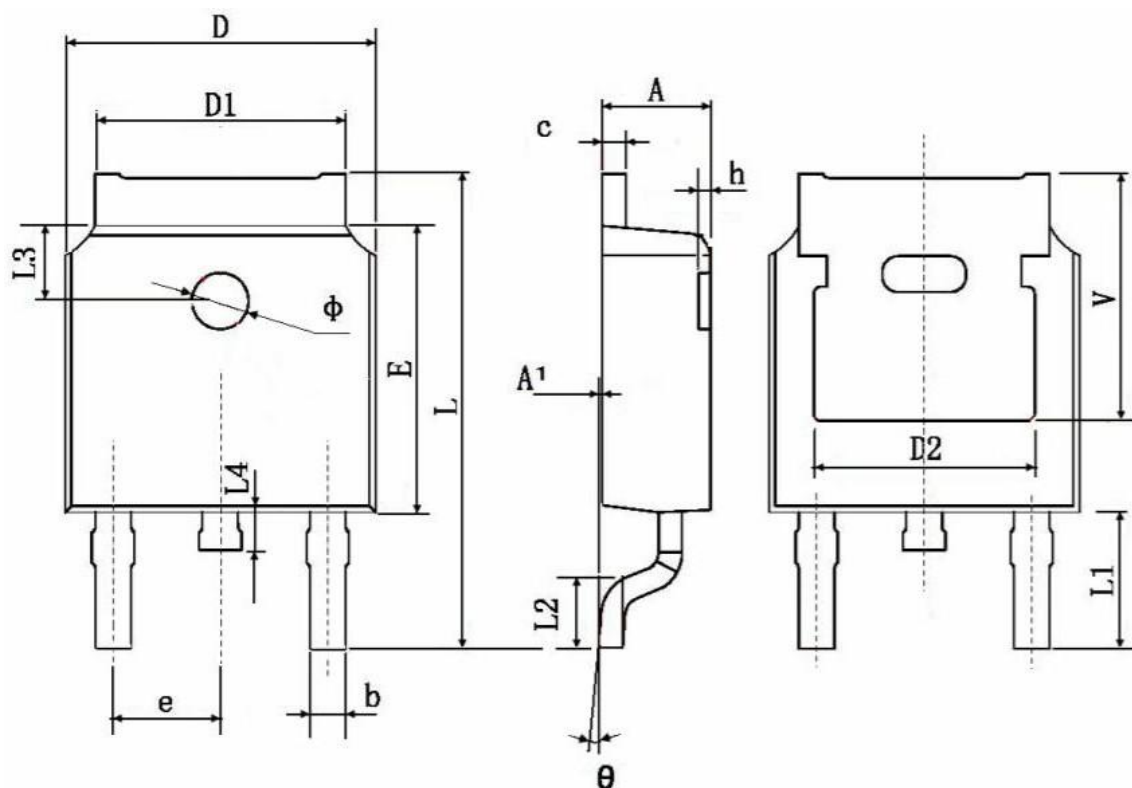
Fig1 Output Characteristics

Fig2 Transfer Characteristics

Fig3 Rds(on)-Drain current

Fig4 Capacitance vs Vds

Fig5 Rds(on)-Gate Drain voltage

Fig6 Gate Charge


Fig7 Power De-rating

Fig8 Source-Drain Diode Forward


Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	